

Data Sheet Issue:- 1

Medium Voltage Thyristor Types K0769NC600 to K0769NC650

Old Type No.: P410CH65

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V _{DRM}	Repetitive peak off-state voltage, (note 1)	6000-6500	V
V _{DSM}	Non-repetitive peak off-state voltage, (note 1)	6000-6500	V
V _{RRM}	Repetitive peak reverse voltage, (note 1)	6000-6500	V
V _{RSM}	Non-repetitive peak reverse voltage, (note 1)	6100-6600	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
I _{T(AV)}	Mean on-state current, T _{sink} =55°C, (note 2)	769	А
I _{T(AV)}	Mean on-state current. T _{sink} =85°C, (note 2)	535	А
I _{T(AV)}	Mean on-state current. T _{sink} =85°C, (note 3)	330	А
I _{T(RMS)}	Nominal RMS on-state current, T _{sink} =25°C, (note 2)	1506	А
I _{T(d.c.)}	D.C. on-state current, T _{sink} =25°C, (note 4)	1332	А
I _{TSM}	Peak non-repetitive surge t _p =10ms, V _{rm} =0.6V _{RRM} , (note 5)	8600	А
I _{TSM2}	Peak non-repetitive surge t _p =10ms, V _{rm} ≤10V, (note 5)	9500	А
l ² t	$I^{2}t$ capacity for fusing t _p =10ms, V _{rm} =0.6V _{RRM} , (note 5)	370×10 ³	A ² s
l ² t	I ² t capacity for fusing t _p =10ms, V _m ≤10V, (note 5)	451×10 ³	A ² s
-1: /-14	Maximum rate of rise of on-state current (repetitive), (Note 6)	150	A/µs
di⊤/dt	Maximum rate of rise of on-state current (non-repetitive), (Note 6)	300	A/µs
V _{RGM}	Peak reverse gate voltage	5	V
P _{G(AV)}	Mean forward gate power	2	W
P _{GM}	Peak forward gate power	30	W
T _{HS}	Operating temperature range	-40 to +115	°C
T _{stg}	Storage temperature range	-40 to +150	°C

Notes:-

- 1) De-rating factor of 0.13% per °C is applicable for T_j below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 115°C T_j initial.
- 6) V_D =67% V_{DRM} , I_{FG} =2A, $t_r \le 0.5 \mu s$, T_{case} =125°C.

Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
V _{TM}	Maximum peak on-state voltage	-	-	2.75	I _{TM} =1000A	V
V ₀	Threshold voltage	-	-	1.566		V
r _s	Slope resistance	-	-	1.172		mΩ
dv/dt	Critical rate of rise of off-state voltage	1000	-	-	V_D =80% V_{DRM} , linear ramp, gate o/c	V/μs
I _{DRM}	Peak off-state current	-	-	50	Rated V _{DRM}	mA
I _{RRM}	Peak reverse current	-	-	50	Rated V _{RRM}	mA
Vtr	On-state recovery voltage	-	12	-	I _{TM} =2300A, t _p =10ms, T _{case} =25°C	V
V _{GT}	Gate trigger voltage	-	-	3.0		V
I _{GT}	Gate trigger current	-	-	300	Tj=25°C, V _D =10V, I _T =3A	mA
V_{GD}	Gate non-trigger voltage	-	-	0.25	Rated V _{DRM}	V
I _H	Holding current	-	-	1000	Tj=25°C	mA
t _{gd}	Gate-controlled turn-on delay time	-	0.5	1.5	V _D =67%V _{DRM} , I _{TM} =1000A, di/dt=10A/µs,	μs
t _{gt}	Turn-on time	-	2.8	4.0	I _{FG} =2A, t _r =0.5μs, Τ _j =25°C	μs
Q _{rr}	Recovered charge	-	3100	-		μC
Q _{ra}	Recovered charge, 50% Chord	-	2000	2400	I _{TM} =1000A, t _p =1000μs, di/dt=10A/μs,	μC
I _{rm}	Reverse recovery current	-	135	-	V _r =50V	А
t _{rr}	Reverse recovery time, 50% Chord	-	30	-		μs
t.	Turn-off time	-	900	-	I _{TM} =1000A, t _p =1000μs, di/dt=10A/μs, V _r =50V, V _{dr} =33%V _{DRM} , dV _{dr} /dt=20V/μs	μs
t _q		-	1200	-	I _{TM} =1000A, t _p =1000µs, di/dt=10A/µs, V _r =50V, V _{dr} =33%V _{DRM} , dV _{dr} /dt=200V/µs	μο
Du an s	Thermal resistance, junction to heatsink	-	-	0.024	Double side cooled	K/W
R _{th(j-hs)}		-	-	0.048	Single side cooled	K/W
F	Mounting force	19	-	26		kN
Wt	Weight	-	510	-		g

Notes:-

1) Unless otherwise indicated $T_j=115^{\circ}C$.

Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	V _{DRM} V _{DSM} V _{RRM} V	V _{RSM} V	V _D V _R DC V
60	6000	6100	3000
61	6100	6200	3050
62	6200	6300	3100
63	6300	6400	3150
64	6400	6500	3200
65	6500	6600	3250

2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T_i below 25°C.

4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

5.0 Frequency Ratings

The curves illustrated in figures 17 & 18 are for guidance only and are superseded by the maximum ratings shown on page 1. For operation above line frequency, please consult the factory for assistance.

6.0 Snubber Components

When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

7.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 300A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 150A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

8.0 Square wave frequency ratings

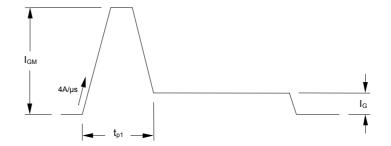
These ratings are given for load component rate of rise of on-state current of 50A/µs.

9.0 Duty cycle lines

The 100% duty cycle is represented on the frequency ratings by a straight line. Other duties can be included as parallel to the first.

10.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{GM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (t_{p1}) should be 20µs or sufficient to allow the anode current to reach ten times I_L, whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current I_G should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .

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11.0 Computer Modelling Parameters

11.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_0 + \sqrt{V_0^2 + 4 \cdot ff \cdot r_s \cdot W_{AV}}}{2 \cdot ff \cdot r_s} \quad \text{and:} \quad \begin{aligned} W_{AV} = \frac{\Delta T}{R_{th}} \\ \Delta T = T_{j \max} - T_{Hs} \end{aligned}$$

Where V_0 =1.566V, r_s =1.172m Ω ,

 R_{th} = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance								
Conduction Angle 30° 60° 90° 120° 180° 270° d.c.							d.c.	
Square wave Double Side Cooled	0.0293	0.0285	0.0278	0.0271	0.0261	0.0249	0.024	
Square wave Single Side Cooled	0.0534	0.053	0.0524	0.0518	0.0509	0.0497	0.048	
Sine wave Double Side Cooled	0.0286	0.0276	0.0269	0.0263	0.0248			
Sine wave Single Side Cooled	0.0531	0.0523	0.0517	0.0511	0.0497			

Form Factors								
Conduction Angle 30° 60° 90° 120° 180° 270° d.c							d.c.	
Square wave	3.464	2.449	2	1.732	1.414	1.149	1	
Sine wave	3.98	2.778	2.22	1.879	1.57			

11.2 Calculating V_T using ABCD Coefficients

The on-state characteristic I_T vs. V_T , on page 6 is represented in two ways;

- (i) the well established V_0 and r_s tangent used for rating purposes and
- (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in terms of I_T given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

	25°C Coefficients		115°C Coefficients	
Α	3.3100044	A 0.7108278		
В	-0.329322	В	0.1494583	
С	7.352344×10 ⁻⁴	С	1.110708×10 ⁻³	
D	0.02672716	D	-3.287414×10 ⁻³	

11.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}} \right)$$

Where p = 1 to *n*, *n* is the number of terms in the series and:

- t = Duration of heating pulse in seconds.
- r_{t} = Thermal resistance at time t.
- r_p = Amplitude of p_{th} term.
- τ_p = Time Constant of r_{th} term.

The coefficients for this device are shown in the tables below:

	D.C. Double Side Cooled								
Term	Term 1 2 3 4 5								
rp	0.01249139	6.316833×10 ⁻³	1.850855×10 ⁻³	1.922045×10 ⁻³	6.135330×10 ⁻⁴				
τρ	τ_{ρ} 0.8840810 0.1215195 0.03400152 6.742908×10 ⁻³ 1.326292×10 ⁻³								

D.C. Single Side Cooled									
Term	Term 1 2 3 4 5 6								
rp	0.02919832	4.863568×10 ⁻³	3.744798×10 ⁻³	6.818034×10 ⁻³	2.183558×10 ⁻³	1.848294×10 ⁻³			
τρ	6.298105	3.286174	0.5359179	0.1186897	0.02404574	3.379476×10 ⁻³			

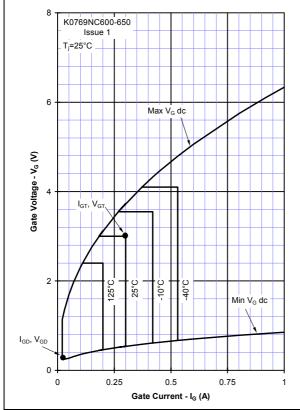
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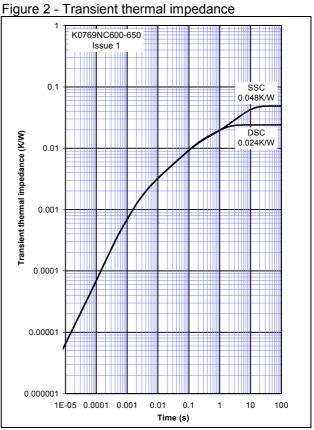
Figure 1 - On-state characteristics of Limit device

<u>Curves</u>

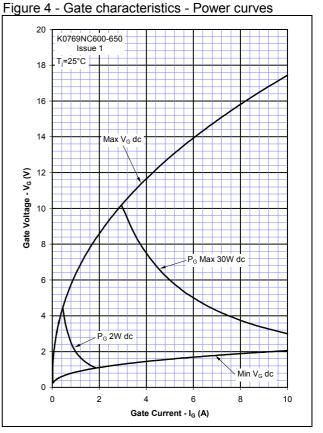
10000 K0769NC600-650 Issue 1 0.1 Transient thermal impedance (K/W) Instantaneous On-state current - I $_{TM}$ (A) 0.01 T_i = 25°C T_i = 115°C 1000 0.001 0.0001 0.00001 100 0.000001 0 2 3 5 6 4 7 1 Instantaneous On-state voltage - V_{TM} (V)











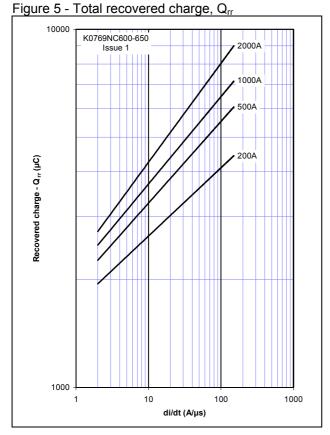
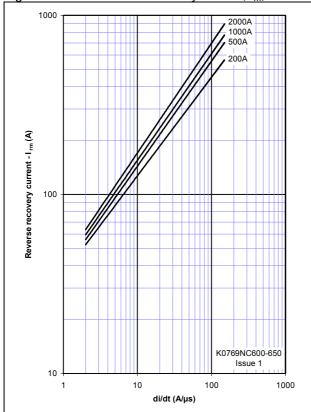
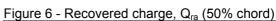
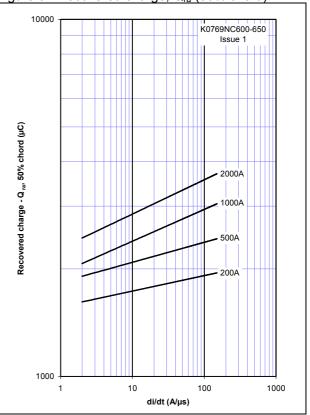


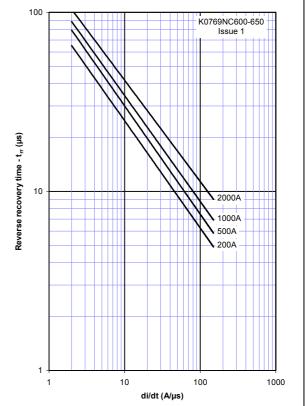
Figure 7 - Peak reverse recovery current, Im











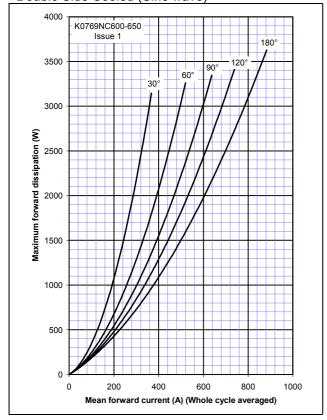
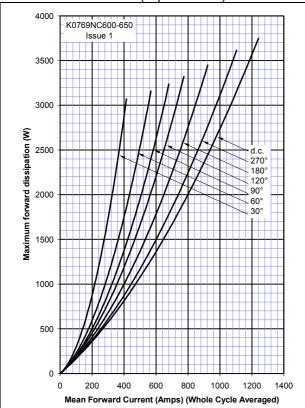


Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

Figure 11 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)



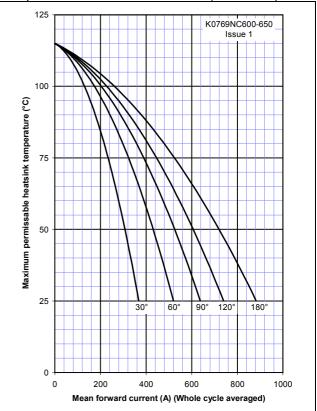
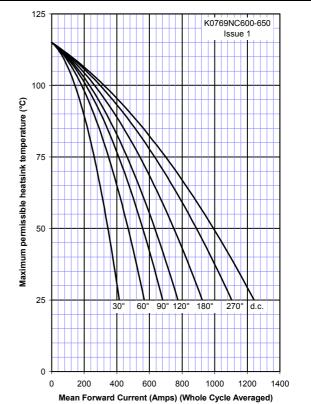


Figure 10 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)

Figure 12 – On-state current vs. Heatsink temperature – Double Side Cooled (Square wave)



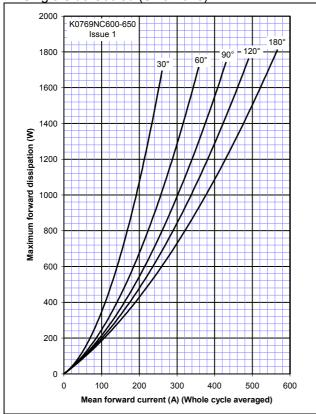
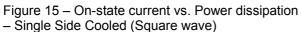
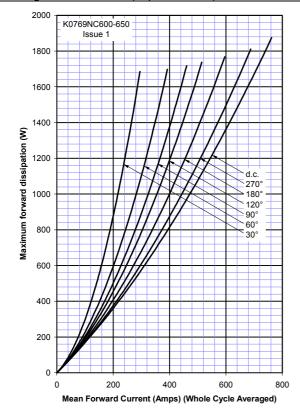


Figure 13 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)





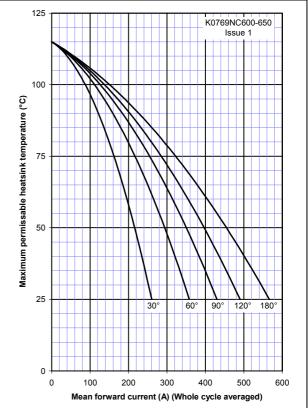


Figure 16 – On-state current vs. Heatsink

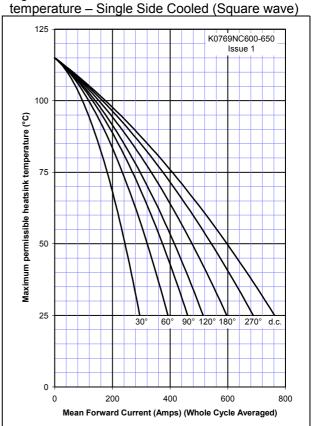


Figure 14 – On-state current vs. Heatsink temperature – Single Side Cooled (Sine wave)

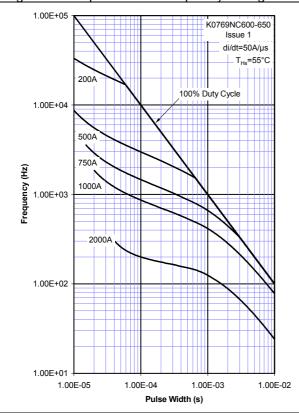


Figure 17 – Square Wave Frequency Ratings

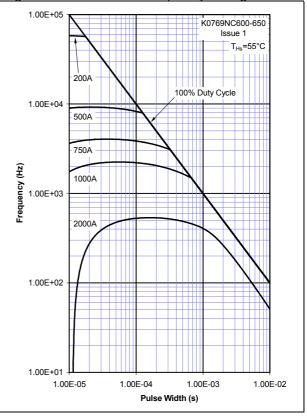


Figure 19 - Maximum surge and I²t Ratings

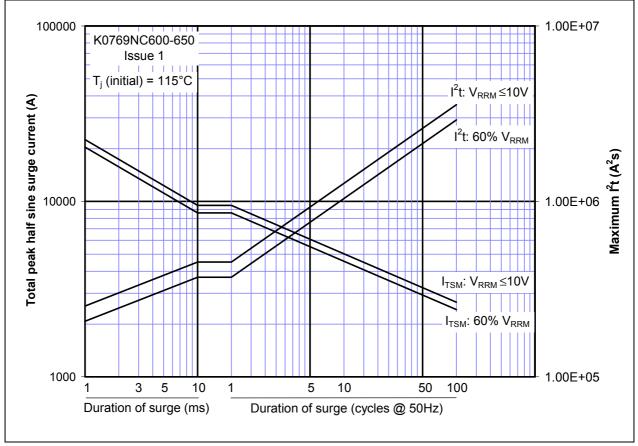


Figure 18 – Sine Wave Frequency Ratings

Outline Drawing & Ordering Information

